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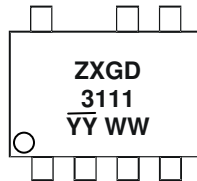
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



Ordering Information (Note 4)

Product	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
ZXGD3111N7TC	ZXGD3111	13	12	2,500

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information


ZXGD = Product Type Marking Code, Line 1
 3111 = Product Type Marking Code, Line 2
 YY = Year (ex: 17 = 2017)
 WW = Week (01 to 53)

Absolute Maximum Ratings (Voltage relative to GND, @T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Supply Voltage	V _{CC}	25	V
Drain Pin Voltage	V _D	-3 to 200	V
Gate Output Voltage	V _G	-3 to V _{CC} +3	V
Gate Driver Peak Source Current	I _{SOURCE}	2	A
Gate Driver Peak Sink Current	I _{SINK}	5	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

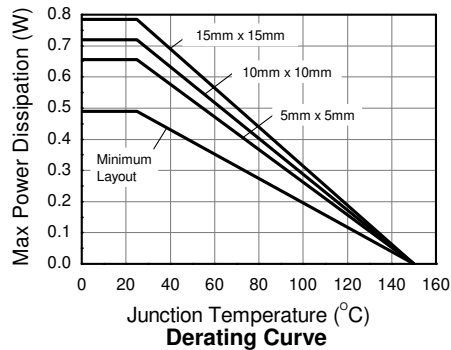
Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor	P _D	490	mW mW/°C
		3.92	
		655	
		5.24	
		720	
Thermal Resistance, Junction to Ambient	R _{θJA}	5.76	°C/W
		785	
		6.28	
		255	
Thermal Resistance, Junction to Lead	R _{θJL}	191	°C/W
		173	
		159	
Operating and Storage Temperature Range	T _J , T _{STG}	-50 to +150	°C

ESD Ratings (Note 10)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge – Human Body Model	ESD HBM	2,000	V	2
Electrostatic Discharge – Machine Model	ESD MM	200	V	B

- Notes:
5. For a device surface mounted on minimum recommended pad layout FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
 6. Same as Note 5, except Pin 3 (V_{CC}) and pins 5 & 6 (PGND) are both connected to separate 5mm x 5mm 1oz copper heat-sinks.
 7. Same as Note 6, except both heat-sinks are 10mm x 10mm.
 8. Same as Note 6, except both heat-sinks are 15mm x 15mm.
 9. Thermal resistance from junction to solder-point at the end of each lead on pins 2 & 3 (GND) and pins 5 & 6 (V_{CC}).
 10. Refer to JEDEC specification JESD22-A114 and JESD22-A11.

Thermal Derating Curve



Electrical Characteristics (@V_{CC} = 12V, T_A = +25°C, unless otherwise specified.)

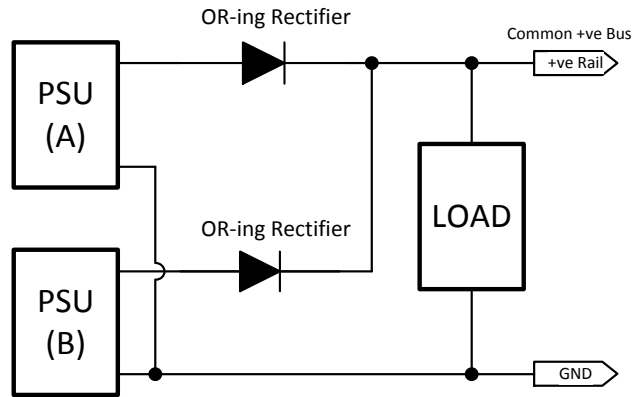
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Input Supply						
Operating Supply Voltage	V _{CC}	4	—	20	V	
Quiescent Current	I _Q	—	200	—	μA	-0.6V ≤ V _{DRAIN} ≤ 200V
Gate Driver						
Gate Peak Source Current	I _{SOURCE}	—	0.66	—	A	C _L = 47nF
Gate Peak Sink Current	I _{SINK}	—	3.3	—		
Gate Peak Source Current (Note 11)	I _{SOURCE}	1	—	—	A	V _{GATE} = 5V & V _{DRAIN} = -1V
Gate Peak Sink Current (Note 11)	I _{SINK}	1.8	—	—	A	V _{GATE} = 5V & V _{DRAIN} = 1V
Detector Under DC Condition						
Turn-Off Threshold Voltage	V _T	-5	-3	-1	mV	V _G ≤ 1V
Gate Output Voltage	V _{G(OFF)}	—	0.1	0.3	V	V _{DRAIN} ≥ 0mV & V _{CC} = 12V
	V _G	—	9.2	—		V _{DRAIN} = -8mV & V _{CC} = 12V
	V _{G(OFF)}	—	0.1	0.3		V _{DRAIN} ≥ 0mV & V _{CC} = 4V
	V _G	—	3.2	—		V _{DRAIN} = -8mV & V _{CC} = 4V
	V _{G(OFF)}	—	0.1	0.3		V _{DRAIN} ≥ 0mV & V _{CC} = 20V
	V _G	—	12	—		V _{DRAIN} = -8mV & V _{CC} = 20V
Switching Performance						
Turn-On Propagation Delay	t _{D(RISE)}	—	400	—	ns	C _L = 47nF Rise and Fall Measured 10% to 90% Refer to Application Test Circuit Below
Gate Rise Time	t _R	—	695	—		
Turn-Off Propagation Delay	t _{D(FALL)}	—	400	—		
Gate Fall Time	t _F	—	131	—		

Note: 11. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

Layout Considerations

The GATE Pin should be close to the MOSFET gate to minimize trace resistance and inductance to maximize switching performance. While the V_{CC} to GND Pin needs an X7R type capacitor closely decoupling the supply. Trace widths should be maximized in the high current paths through the MOSFET and ground return loop in order to minimize the effects of circuit resistance and inductance. The ground return loop should also be as short as possible. For thermal consideration, the main heat path is from Pin 3 (V_{CC}), and pins 5 and 6 (PGND). For best thermal performance, the copper area connected to Pin 3 (V_{CC}), and pins 5 and 6 (PGND) should be maximized.

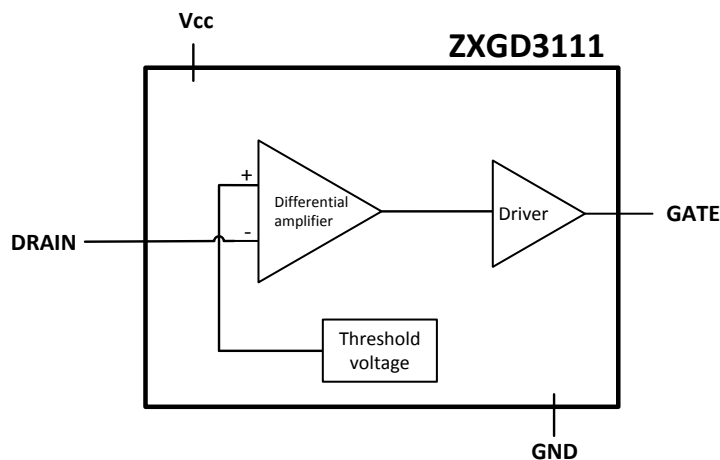
Active OR'ing or (N+1) Redundancy Application



Critical systems require fault-tolerant power supply that can be achieved by paralleling two or more PSUs into (N+1) redundancy configuration. During normal operation, usually all PSUs equally share the load for maximum reliability. If one of the PSUs is unplugged or fails, then the other PSU fully supports the load. To avoid the faulty PSU from affecting the common bus, then an OR'ing rectifier blocks the reverse current flow into the faulty PSU. Likewise during hot-swapping, the OR'ing rectifiers isolate a PSU's discharged output capacitors from the common bus.

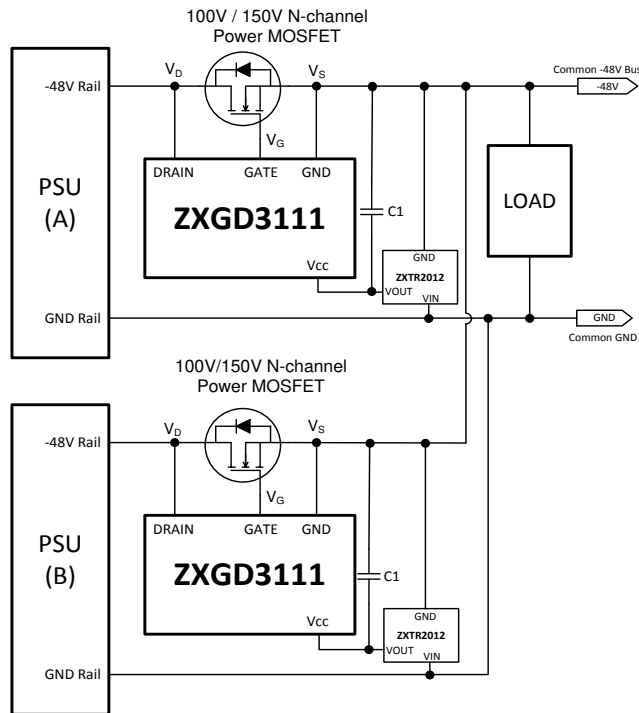
As the load current is in the tens of amps then a standard rectifier has a significant forward voltage drop. This both wastes power and significantly drops the potential on low voltage rails. Hence, very low $R_{DS(ON)}$ Power MOSFETs can replace the standard rectifiers and the ZXGD311 controls the MOSFET as an ideal diode.

Functional Block Diagram

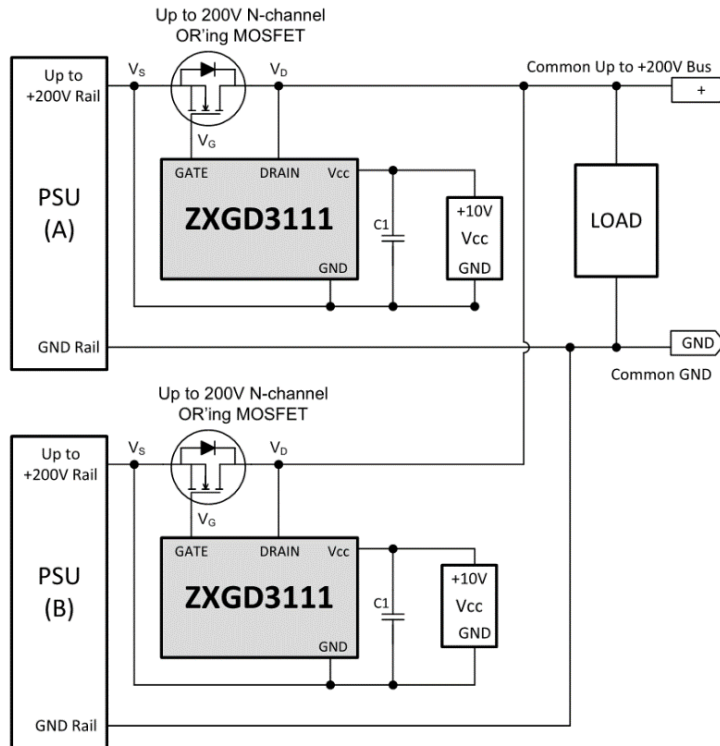


The device is comprised of a differential amplifier and high current driver. The differential amplifier acts as a detector and monitors the DRAIN-to-GND Pin voltage difference. When this difference is less than the threshold voltage (V_T), then a positive output voltage approaching V_{CC} is given on the GATE Pin. If $V_{CC} > 12V$, then the GATE-to-GND will clamp at 12V. Conversely, when the DRAIN-to-GND Pin voltage difference is greater than V_T , then GATE Pin voltage is rapidly reduced towards the GND voltage.

Typical Application Circuits



Focus Application of the ZXGD3111 OR'ing Controller is for Redundant Low-Side -48V Power Supply Rail
ZXR2012 (HV input, 12V output regulator) is suggested to power the V_{CC} of ZXGD3111 from high voltage rail.

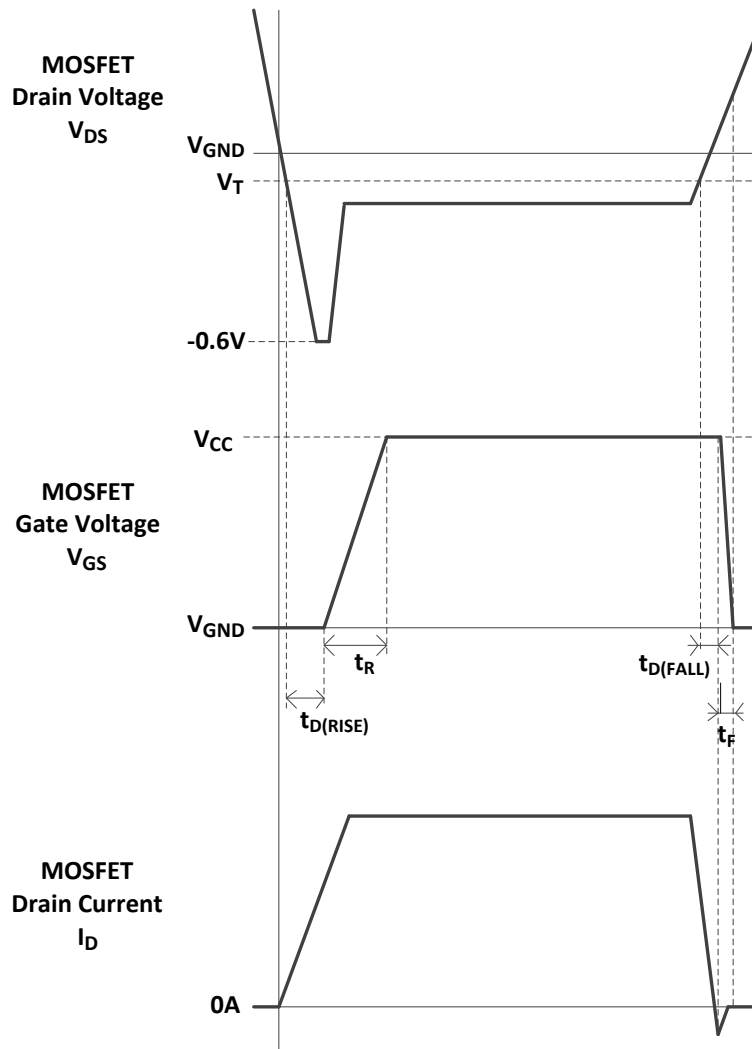


Example of the ZXGD3111 OR'ing Controller in a Redundant High-Side +48V Power Supply Rail with V_{CC} Supply

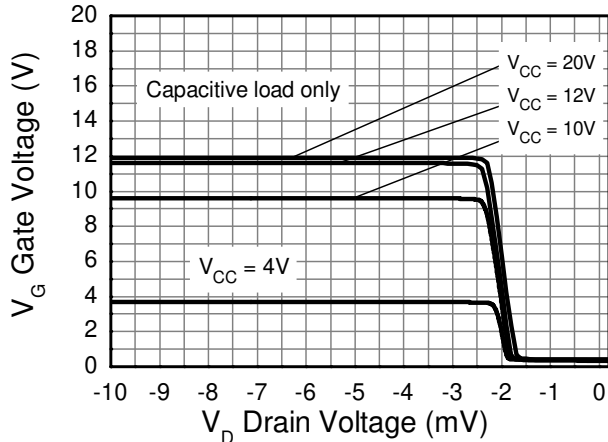
Operation in Typical Application

The ZXGD3111 operation is described step-by-step with reference to the typical application circuits and the timing diagram below:

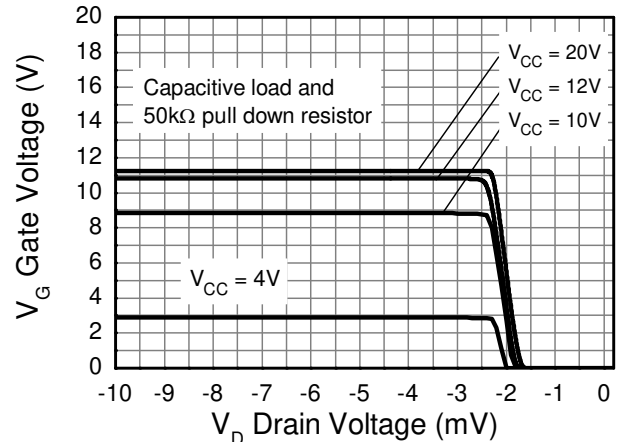
1. The ZXGD3111 differential amplifier monitors the MOSFET's drain-source voltage (V_{DS}).
2. At system start up, the MOSFET body diode is forced to conduct current from the input PSU to the load and V_{DS} is approximately $-0.6V$ as measured by the differential amplifier between DRAIN-to-GND pins.
3. As $V_{DS} < V_T$ (threshold voltage), the differential amplifier outputs a positive voltage approaching V_{CC} with respect to GND. This feeds the driver stage from which the GATE Pin voltage rises towards V_{CC} . If $V_{CC} > 12V$, then the GATE-to-GND will clamp at $12V$.
4. The sourcing current out of the GATE Pin drives the MOSFET gate to enhance the channel and turn it on.
5. If a short condition occurs on the input PSU, it causes the MOSFET V_{DS} to increase.
6. When $V_{DS} > V_T$, then the differential amplifier's output goes to GND and the driver stage rapidly pulls the GATE Pin voltage to GND, turning off the MOSFET channel. This prevents high reverse current flow from the load to the PSU which could pull down the common bus voltage causing catastrophic system failure.



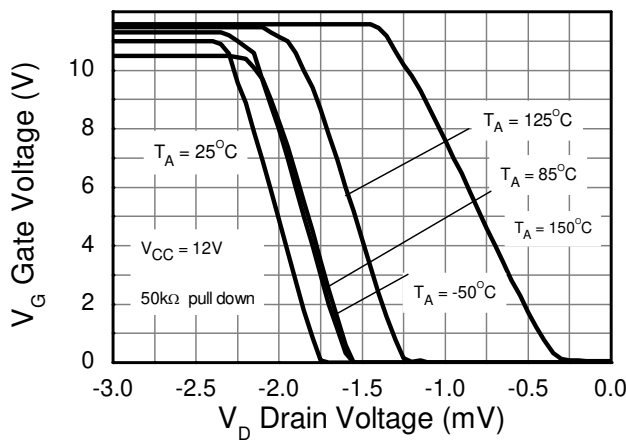
Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)



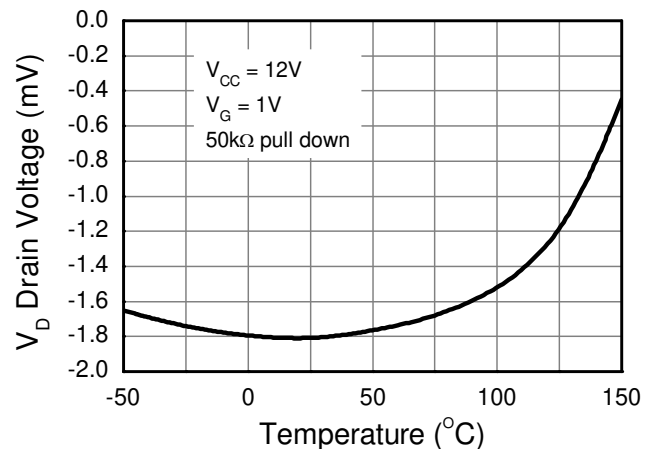
Transfer Characteristic



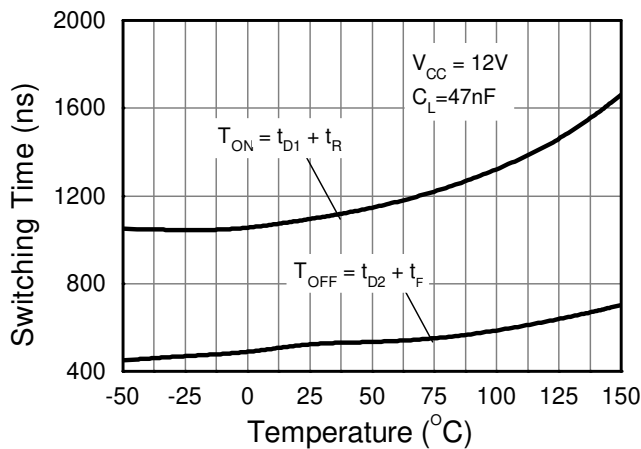
Transfer Characteristic



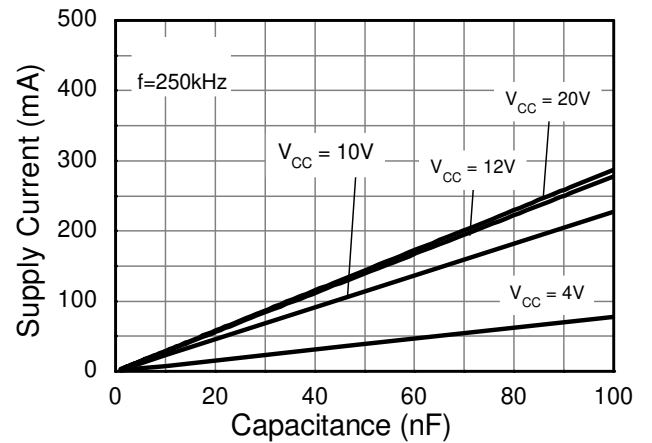
Transfer Characteristic



Drain Sense Voltage vs Temperature

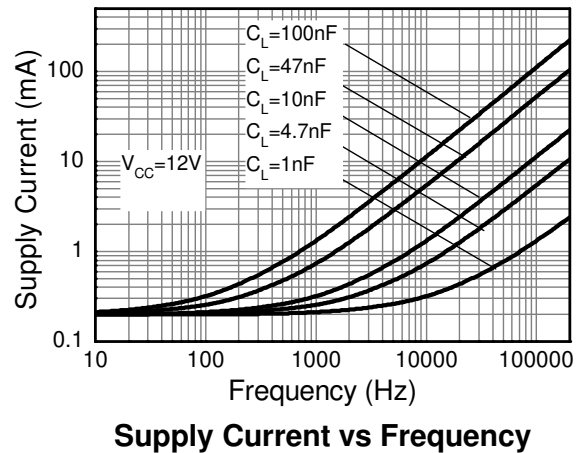
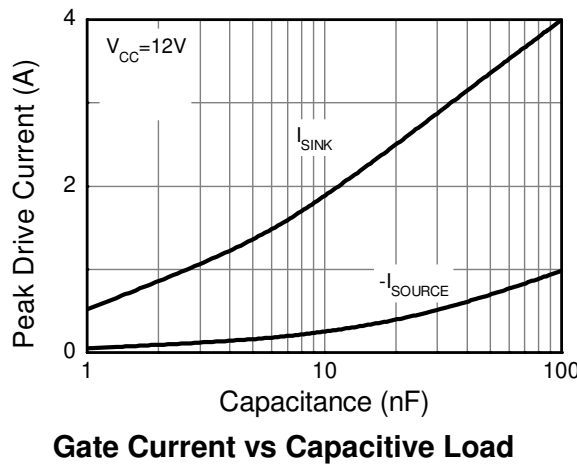
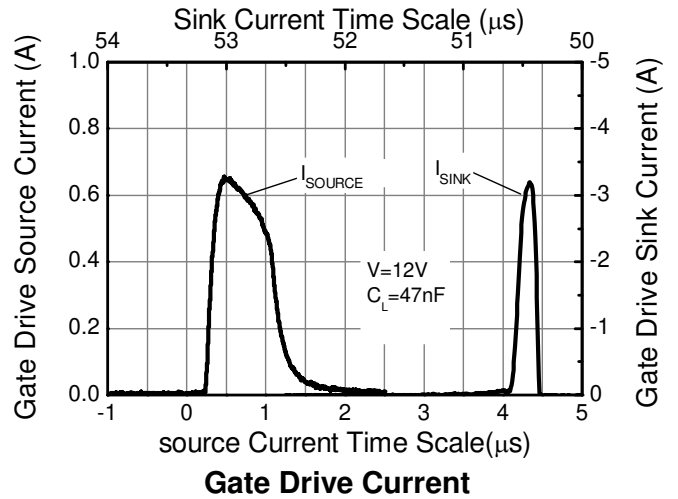
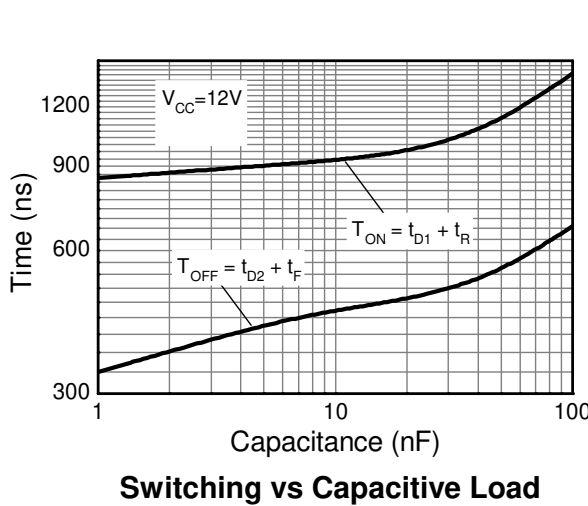
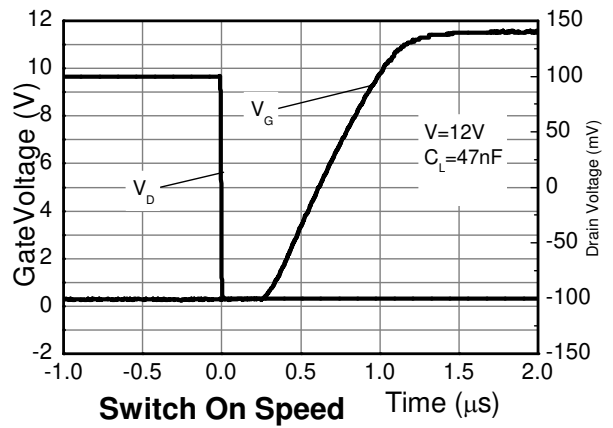
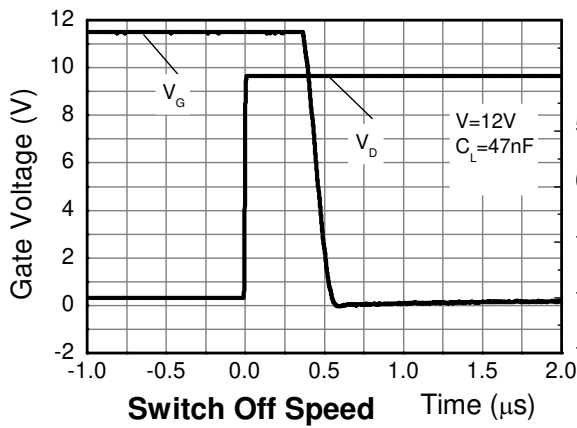


Switching vs Temperature



Supply Current vs Capacitive Load

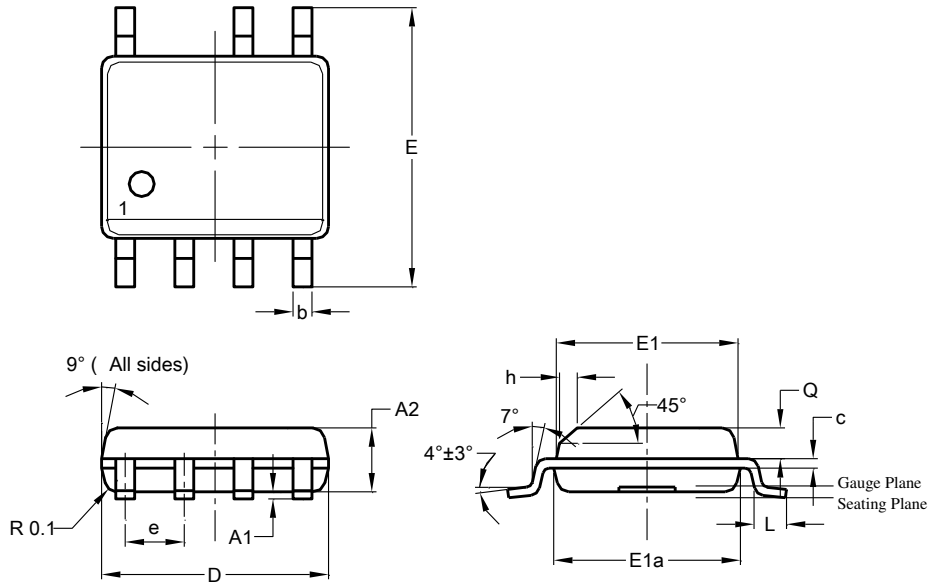
Typical Electrical Characteristics (Cont.) (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)



Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-7

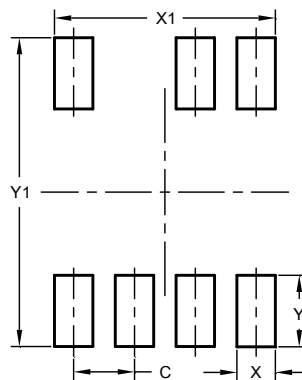


SO-7			
Dim	Min	Max	Typ
A2	1.40	1.50	1.45
A1	0.10	0.20	0.15
b	0.30	0.50	0.40
c	0.15	0.25	0.20
D	4.85	4.95	4.90
E	5.90	6.10	6.00
E1	3.80	3.90	3.85
E1a	3.85	3.95	3.90
e	—	—	1.27
h	—	—	0.35
L	0.62	0.82	0.72
Q	0.60	0.70	0.65
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-7



Dimensions	Value (in mm)
C	1.270
X	0.802
X1	4.612
Y	1.505
Y1	6.500

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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